



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-04-28
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8HST*CWB068M	A	64BA	2017-04-28
Amount	UoM	Unit type	ST ECOPACK Grade	
70.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.14-2.76-1.94	2	J bend	
Comment	Package: SMA - MDF valid for CPs: SMP50-68 ; SMP30-68			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die backside metal	114
Lead	1.07	soft solder	15257

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8HST*CW8068M					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.903	mg	supplier	die	Silicon (Si)	7440-21-3		0.879	mg	973422	12557
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4430	57
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	5537	71
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.005	mg	5537	71
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	2215	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.008	mg	8859	114
Leadframe	Copper & its alloys	29.806	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.776	mg	998993	425371
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.030	mg	1007	429
Soft solder	Solder	1.161	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.068	mg	919897	15257
				supplier	solder	Silver (Ag)	7440-22-4		0.029	mg	24978	414
				supplier	solder	Tin (Sn)	7440-31-5		0.058	mg	49957	829
				supplier	solder	flux residue	Proprietary		0.006	mg	5168	86
Encapsulation	Other Organic Materials	25.908	mg	supplier	mold compound	Amorphous Silica	7631-86-9		18.939	mg	731010	270557
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		4.923	mg	190018	70329
				supplier	mold compound	Phenol resin	9003-35-4		0.777	mg	29991	11100
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		0.777	mg	29991	11100
				supplier	mold compound	Carbon black	1333-86-4		0.233	mg	8993	3329
				supplier	mold compound	Triphenylphosphine	603-35-0		0.181	mg	6986	2586
Connections coating	Solder	0.741	mg	supplier	solder alloy	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.078	mg	3011	1114
Clip	Copper & its alloys	11.481	mg	supplier	alloy	Tin (Sn)	7440-31-5		0.741	mg	1000000	10586
						Copper ( Cu)	7440-50-8		11.481	mg	1000000	164014